

Title (en)
MOLTEN ALUMINUM-PLATED STEEL WIRE

Title (de)
MIT ALUMINIUMSCHMELZE BESCHICHTETER STAHLDRÄHT

Title (fr)
FIL D'ACIER PLAQUÉ D'ALUMINIUM FONDU

Publication
EP 3650572 A4 20201230 (EN)

Application
EP 17916828 A 20170705

Priority
JP 2017024567 W 20170705

Abstract (en)
[origin: EP3650572A1] A hot-dip aluminum-coated steel wire including a steel wire having a diameter of 0.1 to 0.4 mm on which a plating layer is formed, wherein an elongation at break of the hot-dip aluminum-coated steel wire is 5 to 30%, and a ratio of an average diameter of the steel wire which is taken out from the hot-dip aluminum-coated steel by removing the plating layer per 100 mm in length of the steel wire to the minimum diameter of the steel wire satisfies the formula: [minimum diameter/average diameter] \geq [1-(elongation at break (%)/100)], and a method for producing a hot-dip aluminum-coated steel wire including wire-drawing a hot-dip aluminum-coated steel wire so that a ratio of an average diameter of the steel wire which is taken out from the hot-dip aluminum-coated steel by removing the plating layer per 100 mm in length of the steel wire to the minimum diameter of the steel wire satisfies the above-mentioned formula, and an elongation at break of the hot-dip aluminum-coated steel wire is 5 to 30%.

IPC 8 full level
C23C 2/12 (2006.01); **C23C 2/26** (2006.01); **C23C 2/38** (2006.01)

CPC (source: EP US)
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C23C 2/52 (2022.08 - EP US)

Citation (search report)
• [XI] EP 3165628 A1 20170510 - NISSHIN STEEL CO LTD [JP]
• [A] JP 2015193877 A 20151105 - NISSHIN STEEL CO LTD
• [A] JP 2011208263 A 20111020 - NISSHIN STEEL CO LTD
• See references of WO 2019008691A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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